Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for processing a substrate which includescomprising the step of drawing a scribe line on a mother substrate and dividing the mother substrate along the drawn scribe line, characterized in that when a <u>plurality of mother substratesubstrates</u> or a <u>plurality of small mother</u> substrates ubstrates, each of which is a portion that has been divided from a mother substrate, is are simultaneously conveyed, each of said mother substrates ubstrates or each of said small mother substrates ubstrates is held through suction of a first main surface of said mother substrate or a first main surface of said small mother substrate using one of a number of suction members, each of which is provided with a suction surface and an axis of rotation, and then, all of said suction members are rotated approximately simultaneously, and thereby, the twofirst main surface and a second main surfacessurface of each of said mother substrates ubstrates or each of said small mother substratesubstrates are turned over in the upward and downward direction, and then the second main surface of each of said mother substrates or each of said small mother substrates is sucked by a suction member for receiving a substrate provided with a suction surface which is movable to a such a location as to face said second main surface, and each of said mother substrates or each of said small mother substrates is passed in the upward downward direction while being held.

- 2. (Currently Amended) The method for processing a substrate according to claim 1, wherein all of the suction members are rotated around rotational the axes which extend of rotation of said suction members are aligned parallel to each other and the axes of rotation of said suction members extend in thea longitudinal direction of the suction members and passespass through approximately thea center portion in thea width in the direction perpendicular to the longitudinal direction of each suction member.
- 3. (Original) The method for processing a substrate according to claim 1, characterized in that a mother substrate is divided in advance into small mother substrates in strip form, and each of the divided small mother substrates in strip form is sucked and held by any one suction member.
- 4. (Original) The method for processing a substrate according to claim 2, characterized in that the distance between the axis lines of the rotational axes of the respective suction members is changed before or at the time of rotation of said number of suction members.
- 5. (Currently Amended) The A method for processing a-substrate according to elaim 4 comprising the step of drawing a scribe line on a mother substrate and dividing the mother substrate along the drawn scribe line, characterized in that when a mother substrate or a small mother substrate which is a portion that has been divided from a mother substrate is conveyed, said mother substrate or said small mother substrate is held through suction of a main surface of said mother substrate or said small mother substrate using a number of suction members, each of which is

aligned parallel to each other, extending in a longitudinal direction of the suction members and passing through approximately a center portion in a width direction perpendicular to the longitudinal direction of each suction member, and then, all of said suction members are rotated approximately simultaneously, and thereby, the two main surfaces of said mother substrate or said small mother substrate are turned over in the upward and downward direction and the distance between the axis lines of the rotational axes of the respective suction members is changed before or at the time of rotation of said number of suction members, and thereby, athe mother substrate or athe small mother substrate on which a scribe line is at least partially drawn is divided along a portion of said scribe line.

6.-23. (Canceled)

24. (New) A method for conveying a substrate, characterized in that
one main surface of each of a number of substrates is held through
suction of one of a number of suction members, each of which has a suction surface
and an axis for rotation,

next all of said suction members are rotated approximately simultaneously around the respective axes for rotation, and thereby, two main surfaces of each of said substrates are turned over in the upward and downward direction, and

then the other main surface of each of said substrates that have been turned over is sucked by a suction member for receiving a substrate provided with a suction surface which is movable to a such a location as to face said other main

surface of each of said substrates, and each of said substrates is passed in the upward downward direction while being held.

25. (New) A method for processing a substrate, comprising:

providing a plurality of mother substrates aligned with one another on a scribing table, each of the plurality of mother substrates having a first major surface facing the scribing table and a second major surface facing upwardly;

scribing at least one scribe line across the second major surface of each of the plurality of mother substrates provided on the scribing table;

aligning a first robot having a plurality of first suction members over the scribing table, each of plurality of first suction members being provided with a suction surface and being rotatable about an axis of rotation extending in a longitudinal direction of the suction member, and each of the plurality of first suction members being aligned over the second major surface of a respective one of the plurality of mother substrates provided on the scribing table:

holding the second major surface of each of the plurality of mother substrates by suction against the suction surface of a respective one of the plurality of first suction members;

approximately simultaneously rotating each of the plurality of first suction members 180° about its axis of rotation so that a first major surface of each of the plurality of mother substrates is facing upwardly;

aligning a second robot having a plurality of second suction members over the first major surface of each of the plurality of mother substrates held on the plurality of first suction members of the first robot, each of plurality of second suction members being provided with a suction surface and being rotatable about an axis of rotation

extending in a longitudinal direction of the suction member, and each of the plurality of second suction members being aligned over the first major surface of a respective one of the plurality of mother substrates held on the plurality of first suction members of the first robot;

holding the first major surface of each of the plurality of mother substrates by suction against the suction surface of a respective one of the plurality of second suction members;

aligning the second robot with a table; and

releasing the suction holding the first major surface of each of the plurality of mother substrates against the suction surface of a respective one of the plurality of second suction members to mount the plurality of mother substrates on the table with the first major surface of each of the plurality of mother substrates facing upwardly.

- 26. (New) The method for processing a substrate according to claim 25, further comprising scribing at least one scribe line across the first major surface of each of the plurality of mother substrates.
- 27. (New) The method for processing a substrate according to claim 25, wherein each of the plurality of mother substrates comprises a small mother substrate which is a portion that has been divided from a mother substrate.
- 28. (New) The method for processing a substrate according to claim 25, wherein the table is a positioning table.

29. (New) The method for processing a substrate according to claim 25, wherein the table is a scribing table.